



# **KW36/35/34: Arm® Cortex®-M0+ | Kinetis® KW36/35/34 Bluetooth Low Energy 32-bit MCUs | NXP**

## **KW36-35**

Last Updated: Jul 11, 2022

Note: For the latest Bluetooth LE 5.0 features please check the [KW39/38/37](#).

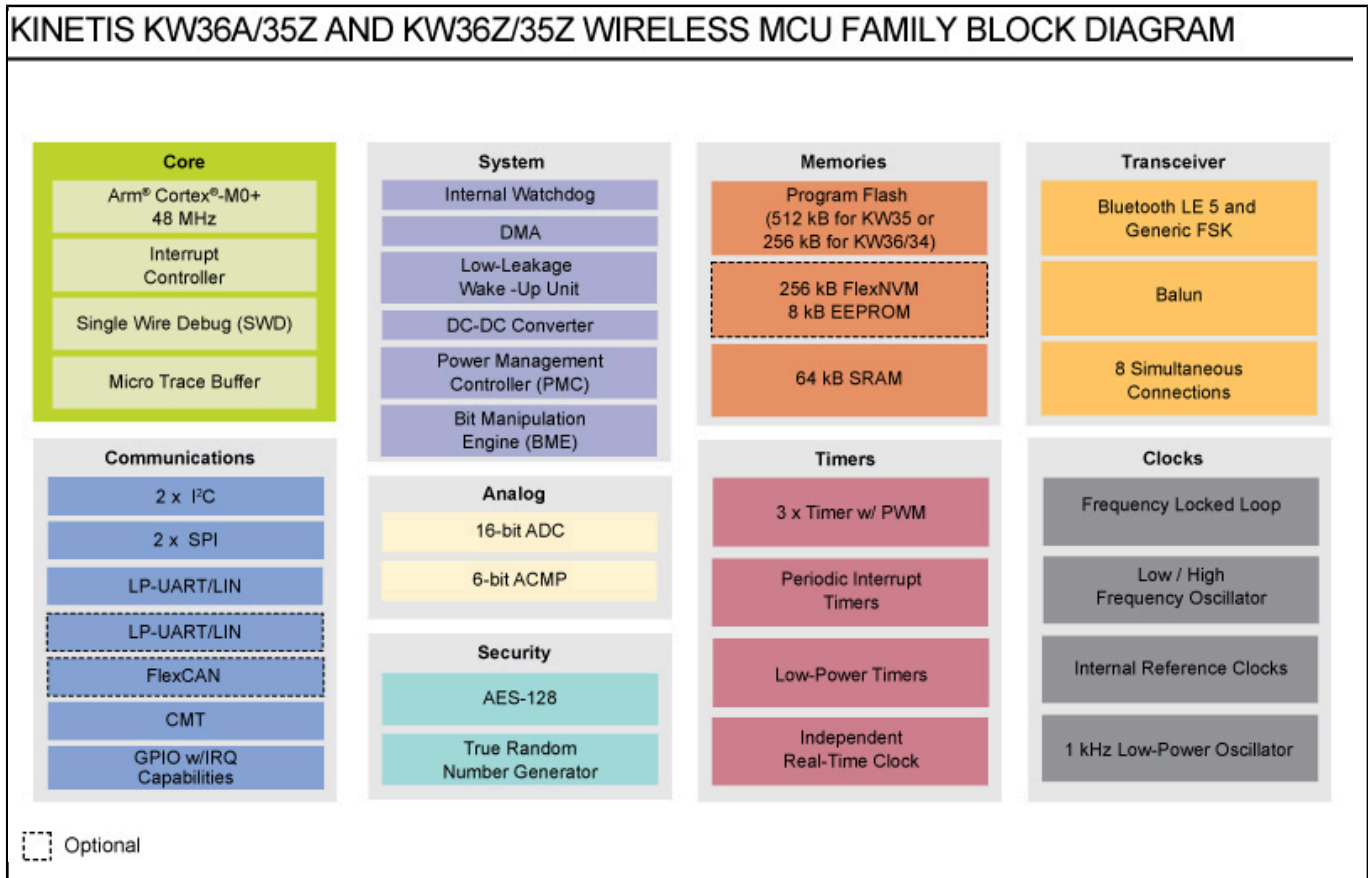
The KW36/35/34 is an ultra-low power, highly integrated single-chip family that enables Bluetooth Low Energy version 5 and Generic FSK (at 250, 500 and 1000 kbps) connectivity for automotive, industrial and medical embedded systems. KW36/35/34 integrates an Arm® Cortex®-M0+ CPU, up to 512 KB Flash and 64 KB SRAM, Bluetooth LE and Generic FSK hardware Link Layers and peripherals optimized to meet the requirements of the target applications. KW36/35/34 supports up to 8 simultaneous Bluetooth LE connections as either a central, a peripheral or any combination.

The KW36 includes an integrated FlexCAN module enabling seamless integration into an automotive or industrial CAN communication network, enabling communication with external control and sensor monitoring devices over Bluetooth LE. The FlexCAN module can support CAN's flexible data-rate (CAN FD) protocol for increased bandwidth and lower latency.

The KW36/35/34 devices can be used as a "BlackBox" modem in order to add Bluetooth LE or Generic FSK connectivity to an existing host MCU or MPU, or may be used as a standalone smart wireless sensor with embedded application where no host controller is required.

The Kinetis KW36A/35A/34A MCUs feature AEC Q100-Grade 2 temperature range qualification while the KW36Z/35Z feature and Industrial qualification.

# Kinetis KW36/35/34 Wireless MCU Family Block Diagram Block Diagram



View additional information for [KW36/35/34: Arm® Cortex®-M0+|Kinetis® KW36/35/34 Bluetooth Low Energy 32-bit MCUs | NXP](#).

**Note:** The information on this document is subject to change without notice.

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